



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



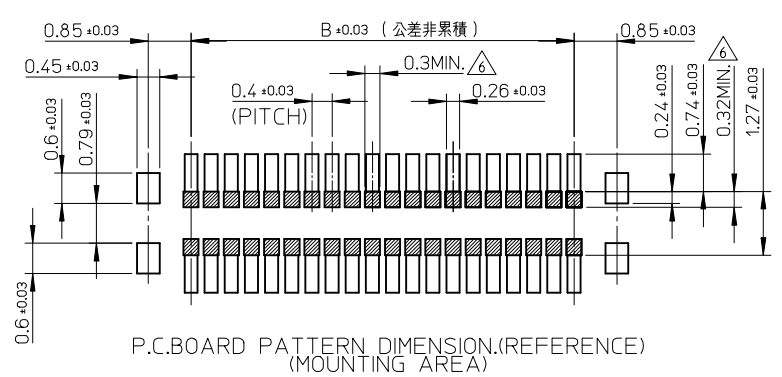
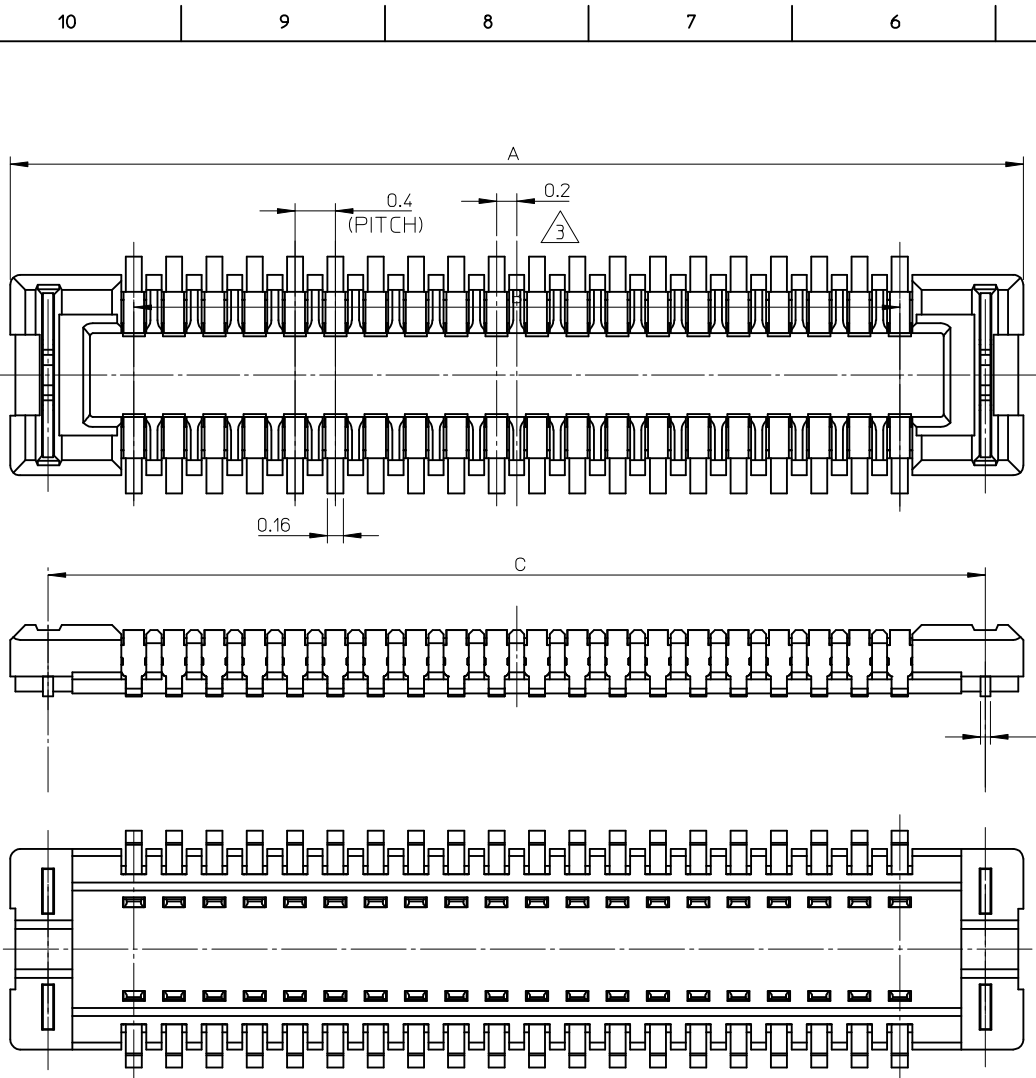
Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





15.3	13.6	16.05	501594-7011	501594-7010	70
12.1	10.4	12.85	501594-5411	501594-5410	54
11.3	9.6	12.05	501594-5011	501594-5010	50
10.1	8.4	10.85	501594-4411	501594-4410	44
9.3	7.6	10.05	501594-4011	501594-4010	40
8.1	6.4	8.85	501594-3411	501594-3410	34
7.3	5.6	8.05	501594-3011	501594-3010	30
6.5	4.8	7.25	501594-2611	501594-2610	26
6.1	4.4	6.85	501594-2411	501594-2410	24
5.7	4.0	6.45	501594-2211	501594-2210	22
5.3	3.6	6.05	501594-2011	501594-2010	20
3.7	2.0	4.45	501594-1211	501594-1210	12
3.3	1.6	4.05	501594-1011	501594-1010	10
C	B	A	EMBOSSED TAPE PACKAGE	MATERIAL NO.	CIRCUIT
			ORDER No.		

REVISED EC NO: J2008-3370 DRW:KSEI 2008/06/17 CHK:D:MSASAO 2008/06/17 APPR:MSASAO 2008/06/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY T. ASAKAWA	DATE 2006/07/10	TITLE 0.4MM PITCH B/B CONN. H=0.9 W=3.4 PLUG ASSY		
	10 OVER 30 UNDER	± 0.25	CHECKED BY M. SASAO	DATE 2006/07/10	MOLEX INCORPORATED		
	30 OVER	± 0.3	APPROVED BY M. SASAO	DATE 2006/07/10	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-501594-005	SHEET NO. 1 OF 2
	ANGULAR ± 3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

注記 NOTES

1.使用材料
MATERIAL

ハウジング：液晶ポリマー (LCP) ガラス充填 UL-94V-0 (黒)
HOSING : LIQUID CRYSTAL POLYMER (GLASS FILLED) UL94V-0 (COLOR:BLACK)

ターミナル：りん青銅 (t=0.08)
TERMINAL : PHOSHOR BRONZE (t=0.08)

金具：りん青銅 (t=0.1)
FITTING NAIL : PHOSHOR BRONZE (t=0.1)

2.メッキ仕様
PLATING

ターミナル
TERMINAL

金メッキ 0.1マイクロメートル以上 (コンタクト部)
GOLD 0.1 MICROMETER MINIMUM (CONTACT AREA)

金メッキ 0.03マイクロメートル以上 (テール部)
GOLD 0.03 MICROMETER MINIMUM (TAIL AREA)

下地メッキ：ニッケルメッキ 1.0 マイクロメートル以上
UNDER PLATING : NICKEL 1.0 MICROMETER MINIMUM

金具
FITTING NAIL

錫メッキ :1.0マイクロメートル以上
TIN PLATING :1.0 MICROMETER MINIMUM

下地メッキ :ニッケル1.0マイクロメートル以上
UNDER PLATING :NICKEL 1.0 MICROMETER MINIMUM

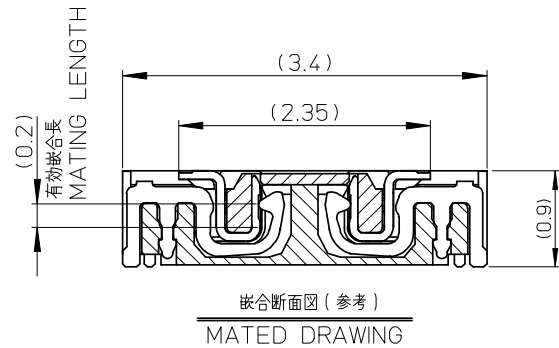
③ (全極数/2)=偶数の場合に適用
APPLY FOR (CIRCUIT/2)=EVEN

4.嵌合相手 : 501591-**10シリーズ
WITH MATE : 501591-**10SERIES

5.テール及び金具の平坦度は、0.1以下
TAIL AND FITTING NAIL COPLANARITY TO BE 0.1 MAXIMUM

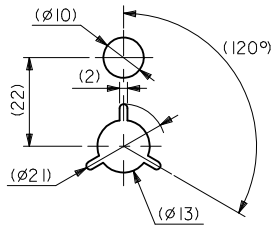
⑥ 斜線部はパターン書き込み禁止範囲と半田禁止範囲を示す。
ただし、斜線部に同一配線を配置する場合はレジストを施し、この部分に半田は無きこと。
NO PATTERN CIRCUIT AND NO SOLDER ALLOWED IN THE SHADED AREA.
HOWEVER, IF NEEDED TO ADD A TRACE OF THE SAME CIRCUIT, PUT THE SOLDER-RESIST,
YET NO SOLDER ALLOWED IN THE AREA.

7.ELV AND RoHS COMPLIANT.

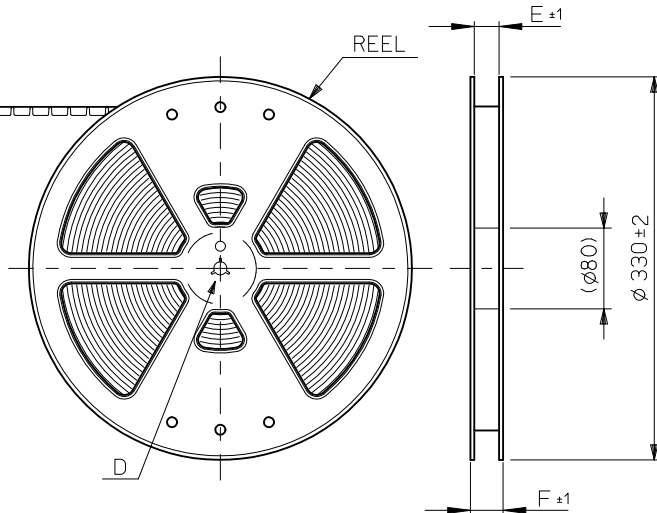


REVISED EC NO: J2008-3370 DRW:KSETO 2008/06/17 CHK:MSASAO 2008/06/17 APPR:MSASAO 2008/06/25 DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY T. ASAKAWA	DATE 2006/07/10	TITLE 0.4MM PITCH B/B CONN. H=0.9 W=3.4 PLUG ASSY			
	10 OVER 30 UNDER	±0.25	CHECKED BY M. SASAO	DATE 2006/07/10	MOLEX INCORPORATED			
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2006/07/10	DOCUMENT NO. SD-501594-005			
	ANGULAR ±3 °		MATERIAL NO. SEE SHEET 1		SHEET NO. 2 OF 2			
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

引き出し方向
PULL OUT DIRECTION

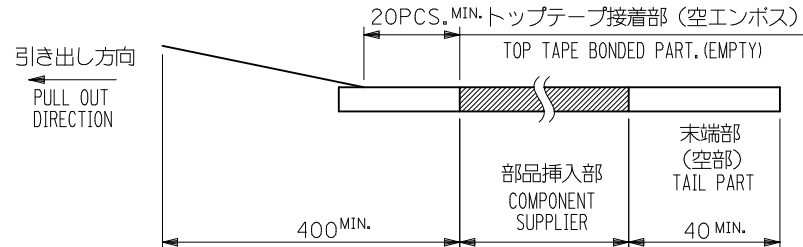


DETAIL D

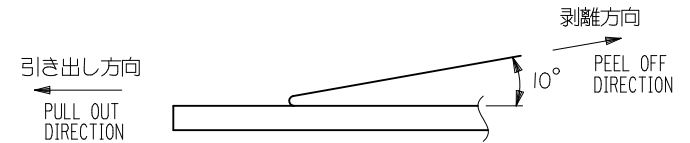


NOTES

- 製品詳細寸法については製品単体図面を参照下さい。
RE DETAILED DIMENSION, SEE PRODUCT DRAWING.
- 梱包数量：3000 個/リール
NUMBER OF CONNECTORS : 3000 PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



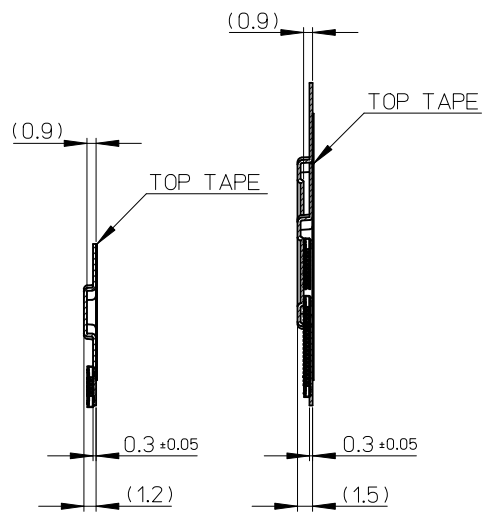
- トップテープの剥離強度：JES-59 参照
剥離方向は下図参照。
PEELING OFF STRENGTH OF TOP TAPE : REFER TO JES-59
PEELING DIRECTION AS SHOWN IN FOLLOWING FIGURE.



- 材料 MATERIAL
キャリアテープ (CARRIER TAPE) : ポリスチレン (POLYSTYRENE)
トップテープ (TOPTAPE) : PET , PE , PEF
リール (REEL) : ポリスチレン (PS) <リサイクル材を含む>
POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>

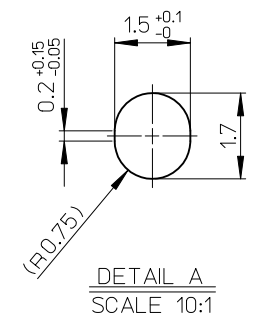
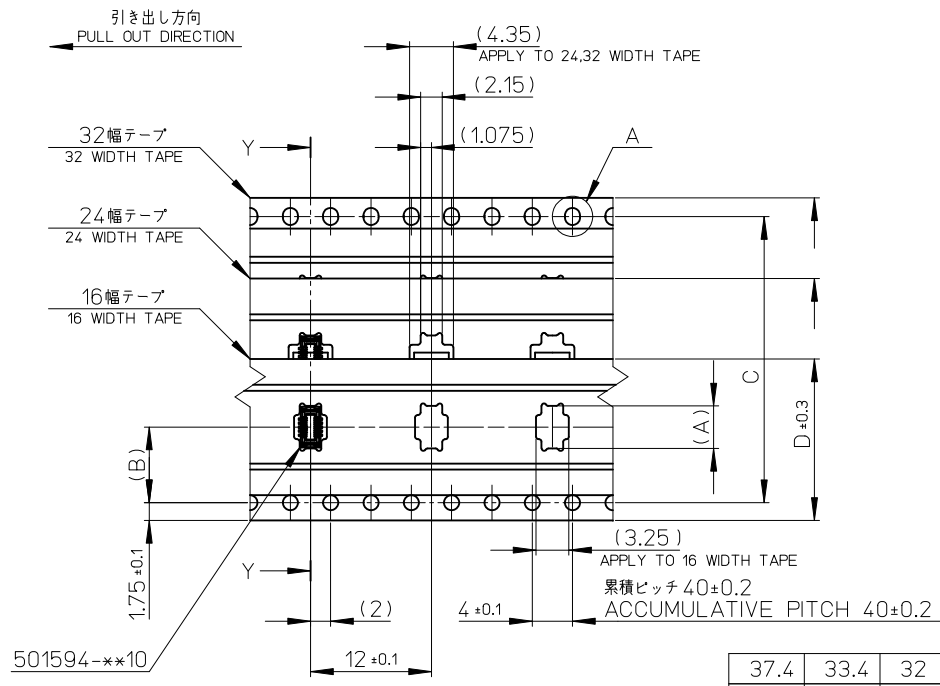
6.ELV AND RoHS COMPLIANT.

REVISED EC NO: J2012-0023 DRWNG: TOYODA 2011/07/05 CHKD: TASAKAWA 2011/07/06 APPR: MSASAO 2011/11/30	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	501594-**11	MODEL NO.	
		10 UNDER	±0.2	DRAWN BY TASAKAWA	DATE 2006/07/10	TITLE	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 OVER 30 UNDER	±0.25	CHECKED BY MSASAO	DATE 2006/07/10	0.4MM PITCH B/B CONN. PLUG ASSY (HGT=0.9) EMBSTP PKG	MOLEX INCORPORATED	SHEET NO. 1 OF 2	
		30 OVER	±0.3	APPROVED BY MSASAO	DATE 2006/07/10				
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE SHEET 1		DOCUMENT NO. SD-501594-006			
				SIZE A3				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	



SECT Y-Y
(FOR 16 WIDTH TAPE)

SECT Y-Y
(FOR 24 WIDTH TAPE
AND 32 WIDTH TAPE)



37.4	33.4	32	28.4	14.2	16.21	501594-7011	70
29.4	25.4	24	—	11.5	13.01	501594-5411	54
					12.21	501594-5011	50
					11.01	501594-4411	44
					10.21	501594-4011	40
					9.01	501594-3411	34
					8.21	501594-3011	30
					7.41	501594-2611	26
21.4	17.4	16	—	7.5	7.01	501594-2411	24
					6.61	501594-2211	22
					6.21	501594-2011	20
F	E	D	C	(B)	4.61	501594-1211	12
					4.21	501594-1011	10
					(A)	MATERIAL NO.	極数 CKT.

REVISED EC NO: J2012-0023 DRW:KTOYODA 2011/07/06 CHK:D:TASAKAWA 2011/07/06 APPR:MSASAO 2011/11/30	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---		DESIGN UNITS METRIC		501594-***11		MODEL NO.
		10 UNDER	± 0.2	DRAWN BY TASAKAWA		DATE 2006/07/10		TITLE		0.4MM PITCH B/B CONN. PLUG ASSY (HGT=0.9) EMBSTP PKG		
		10 OVER 30 UNDER	± 0.25	CHECKED BY MSASAO		DATE 2006/07/10		MOLEX		MOLEX INCORPORATED		
		30 OVER	± 0.3	APPROVED BY MSASAO		DATE 2006/07/10		DOCUMENT NO.		SD-501594-006		
		ANGULAR ± 3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.		SEE TABLE		SHEET NO.		2 OF 2